

BF3510TV

PRELIMINARY DATASHEET

FULL 50-60Hz RECTIFICATION BRIDGE

MAIN PRODUCT CHARACTERISTICS

l _{F(AV)}	35 A
V _{RRM}	1000 V
Tj (max)	150 °C
V _F (max)	1.30 V

FEATURES AND BENEFITS

- COMPACT ISOTOP DESIGN COMPATIBLE WITH FAST DIODES AND TRANSISTORS.
- EXCELLENT THERMAL TRANSFER BETWEEN JUNCTION AND HEATSINK
- UL PENDING

DESCRIPTION

The Bridges series from ST Microelectronics has been designed to allow a better standardization of packages on boards principally designed with ISO-TOP packages. The insulated package of the bridge will be able to sit on heatsink with other components. Single phase and 3-phase high power SMPS, UPS, MOTOR DRIVES and WELD-ING equipment will primarily find advantage in these industry package products.

<image>

Symbol	Param	Value	Unit	
Vrrm	Repetitive peak reverse voltage		1000	V
Vrsm	Non repetitive peak reverse voltage		1000	V
IF(AV) total	Average forward current	35	А	
I _{FSM}	Surge non repetitive forward current 50Hz JEDEC method		300	A
l ² .t	Fusing		660	A ² .s
T _{stg}	Storage temperature range	- 55 to + 150	°C	
Tj	Maximum operating junction temperature		150	°C
Pmax total	Totol power dissipation	50	W	

ABSOLUTE RATINGS AND ELECTRICAL CHARACTERISTICS (per diode unless specified)

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BF3510TV

THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
Rth (j-c)	Junction to case	total	0.5	°C/W

ELECTRICAL CHARACTERISTICS (Per diode) STATIC CHARACTERISTICS

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
I _R *	Reverse leakage current	$V_R = 0.8 V_{RRM}$ $\delta < 2\%$ tp = 5ms	$T_j = 25^{\circ}C$			10	μA
	current		T _j = 125°C			0.2	mA
VF **	Forward voltage drop	IF = 35 A δ < 2%	$T_j = 25^{\circ}C$			1.4	V
		tp = 380µs	Tj = 125°C			1.3	V

Pulse test : * tp = 5 ms, duty cycle < 2 % ** tp = 380 µs, duty cycle < 2 %

For one diode: Pcond = $1.02 \times I_{F(AV)} + 0.008 \times I_{F(RMS)}^2$ Tj = Pcond x 4 x Rth(j-c) + Tc

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PACKAGE MECHANICAL DATA ISOTOP (Plastic)

		DIMENSIONS				
	REF.	Millimeters		Inches		
		Min.	Max.	Min.	Max.	
	Α	11.80	12.20	0.465	0.480	
-	A1	8.90	9.10	0.350	0.358	
	В	7.8	8.20	0.307	0.323	
	С	0.75	0.85	0.030	0.033	
	C2	1.95	2.05	0.077	0.081	
	D	37.80	38.20	1.488	1.504	
	D1	31.50	31.70	1.240	1.248	
	E	25.15	25.50	0.990	1.004	
	E1	23.85	24.15	0.939	0.951	
	E2	24.80	24.80 typ.		0.976 typ.	
	G	14.90	15.10	0.587	0.594	
	G1	12.60	12.80	0.496	0.504	
·	G2	3.50	4.30	0.138	0.169	
	F	4.10	4.30	0.161	0.169	
	F1	4.60	5.00	0.181	0.197	
	Р	4.00	4.30	0.157	0.69	
	P1	4.00	4.40	0.157	0.173	
	S	30.10	30.30	1.185	1.193	
Cooling method : by conduction (C)	anacitano					

Cooling method : by conduction (C) Electrical isolation : $2500V_{(RMS)}$

Capacitance: < 45 pF Inductance: < 5 nH

Recommended torque value: 1.3 N.m (MAX 1.5 N.m) for the 6 x M4 screws. (2 x M4 screws recommended for mounting the package on the heatsink and the 4 screws given with the screw version).
The screws supplied with the package are adapted for mounting on a board (or other types of terminals) with a thickness of 0.6 mm min and

 The screws supplied with the package are adapted for mounting on a board (or other types of terminals) with a thickness of 0.6 mm min and 2.2 mm max.

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
BF3510TV	BF3510TV	ISOTOP	27g without screws	10	Tube

■ Epoxy meets UL94,V0

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